

DZ2420000L

Zener Diode DZ2420000L

Silicon epitaxial planar type

For constant voltage / For surge absorption circuit Capability of withstanding a high surge type DZ2W200 in Power type package

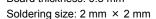
Features

- · Excellent rising characteristics of zener current Iz
- Low zener operating resistance Rz
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: ZJ

Packaging

Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

| Absolute Maximum Ratings Ta = 25 °C | | | | | | | |
|---|--------|-------------|------|--|--|--|--|
| Parameter | Symbol | Rating | Unit | | | | |
| Repetitive peak forward current | IFRM | 500 | mA | | | | |
| Forward current | IF | 400 | mA | | | | |
| Total power dissipation ^{*1} | PT | 2 | W | | | | |
| Non-repetitive reverse power surge *2 | PZSM | 100 | W | | | | |
| Electrostatic discharge *3 | ESD | ±30 | kV | | | | |
| Junction temperature | Tj | 150 | °C | | | | |
| Operating ambient temperature | Topr | -40 to +85 | °C | | | | |
| Storage temperature | Tstg | -55 to +150 | °C | | | | |
| Note: *1 Mounted on ceramics print circuit board. | | | | | | | |
| Board size: 50 mm × 50 mm | | | | | | | |
| Board thickness: 0.8 mm | | | | | | | |



*2 t = 0.1ms

*3 Test method:IEC61000_4_2(C = 150 pF,R = 330 Ω , Contact discharge:10 times)

■ Electrical Characteristics Ta = 25 °C ± 3 °C

| Parameter | Symbol | Conditions | Min | Тур | Max | Unit |
|---|--------|-------------|-------|-------|-------|-------|
| Forward voltage | VF | IF = 200 mA | | | 1.2 | V |
| Zener voltage *1, *2 | VZ | IZ = 10 mA | 19.00 | 20.00 | 21.00 | V |
| Zener operating resistance | RZ | IZ = 10 mA | | | 30 | Ω |
| Reverse current | IR | VR = 14.0 V | | | 10 | μA |
| Temperature coefficient of zener voltage *3 | SZ | IZ = 10 mA | | 19.5 | | mV/°C |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

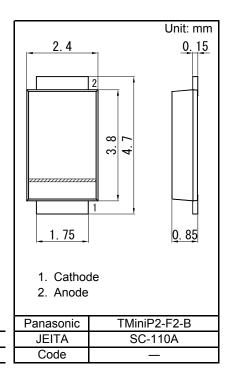
2. Absolute frequency of input and output is 5 MHz.

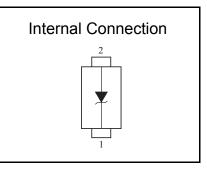
3. *1 The temperature must be controlled 25°C for VZ mesurement.

VZ value measured at other temperature must be adjusted to VZ (25°C)

*2 VZ guaranted 20 ms after current flow.

*3 Tj = 25°C to 150°C

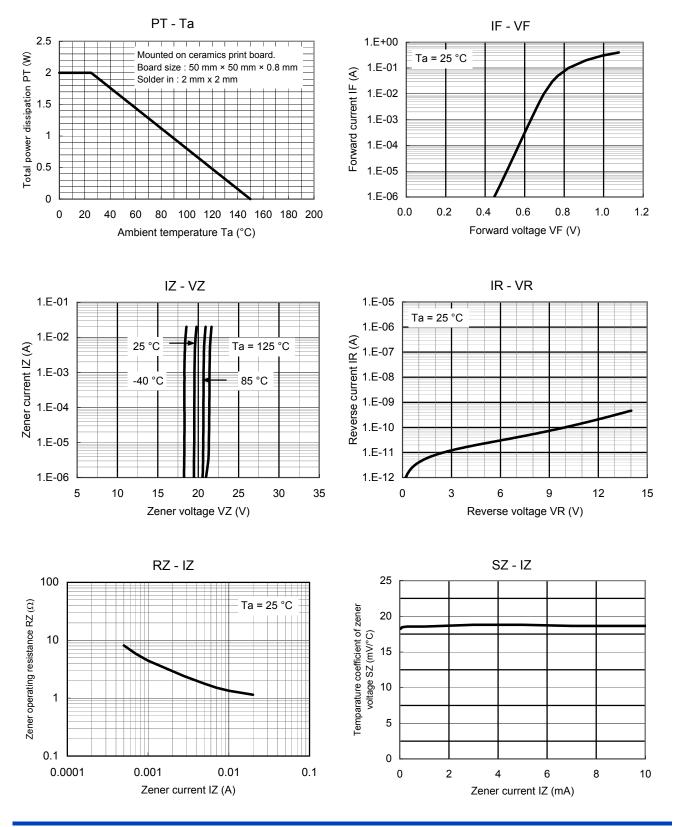






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Technical Data (reference)



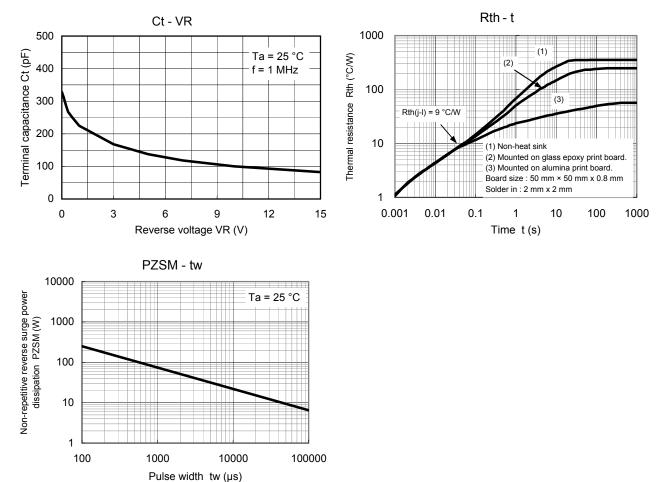
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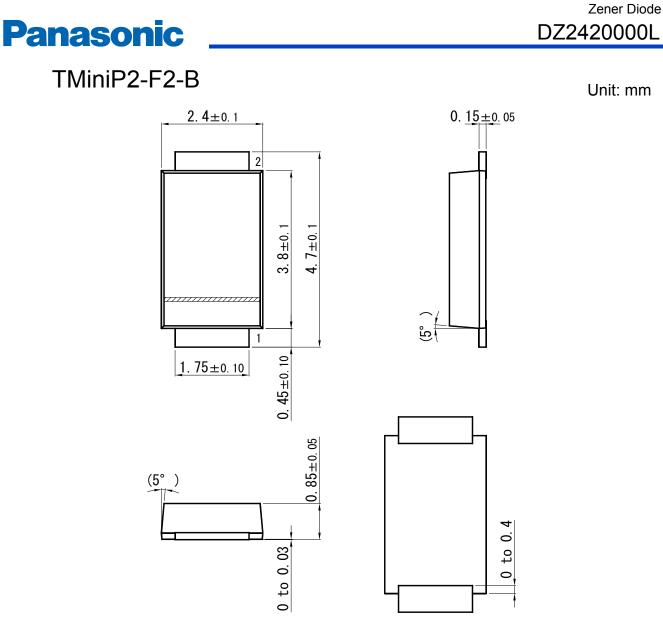
Established : 2011-09-09 Revised : 2013-05-08



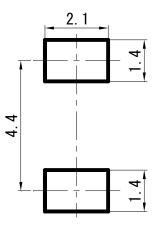
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